Technical specifications	iX 502	iX 302
Maximum output per hour	165 k (121k IPC 9850)	99 k (79k IPC 9850)
Placement quality	< 1 dpm	< 1 dpm
Placement accuracy @ CpK1	35 µm for passives 25 µm for QFP	35 µm for passives 25 µm for QFP
Minimum component size (LxW):	0.25 x 0.125 mm (0201m)	0.25 x 0.125 mm (0201m)
Maximum component size (LxW):	45 x 45 mm (1.77 x 1.77")	45 x 45 mm (1.77 x 1.77")
Maximum component height - Optional	10.5 mm (0.41") 12 mm (0.47")	10.5 mm (0.41") 12 mm (0.47")
Programmable placement force	1.5 to 8 N	1.5 to 8 N
Maximum board size (LxW): - Standard	 515 x 390 mm (20.28 x 15.35")	 475 x 390 mm (18.7 x 15.35")
Minimum board size (LxW): - Standard - Optional	 50 x 50 mm (2 x 2") 50 x 25 mm (2 x 1")	 50 x 50 mm (2 x 2") 50 x 25 mm (2 x 1")
Maximum optional board length	1500 mm (59.06")	800 mm (31.5")
Maximum optional board width	508 mm (20")	508 mm (20")
Board thickness: - Standard	 0.3 to 0.6 mm (0.01 to 0.24")	 0.3 to 0.6 mm (0.01 to 0.24")
Automatic toolbit exchange	Nozzles	Nozzles
Maximum tape feeding positions (8 mm): Single tape feeders	 130	 76
Twin tape feeders	260	156
Feeding options (other feeder types on request)	Tape, stick	Tape, stick
Footprint excl. feeders (LxW)	3,720 x 1,705 mm (146.46 x 67.13")	2,760 x 1,705 mm (108.66 x 67.13")